


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/21/12869	
1.3 Title of PCN	Introduction of subcontractor TSHT for selected products assembled in TSSOP 16 exposed pad package	
1.4 Product Category	See product list	
1.5 Issue date	2021-09-06	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Giuseppe LISI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	TSHT

4. Description of change

	Old	New
4.1 Description	Assembly plant : - Amkor	Assembly plant : - Amkor - TSHT
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Progressing on activities related to process modernization and quality improvement, ST is pleased to announce the introduction of TSHT/China for Assy and Test & Finishing activities for selected products assembled in TSSOP 16 exposed pad package
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	New Finished good codes
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7. Timing / schedule

7.1 Date of qualification results	2021-06-17
7.2 Intended start of delivery	2021-11-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	12869 W1525-2021-6088-New assembly plant TSHT for L7987L (UI76) in HTSSOP 16.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-09-06

9. Attachments (additional documentations)
12869 Public product.pdf 12869 W1525-2021-6088-New assembly plant TSHT for L7987L (UI76) in HTSSOP 16.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L7987	
	L7987L	
	L7987LTR	
	L7987TR	

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Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : Introduction of subcontractor TSHT for selected products assembled in TSSOP 16 exposed pad package

PCN Reference : AMS/21/12869

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L7987	L7987LTR	L7987L
L7987TR		



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Reliability Evaluation Report

New Assembly Plant

SC-Tianshui Huatian-China (TSHT)
HTSSOP 16
TV: L7987L (UI76)

General Information		Locations	
Product Lines	UI7601	Wafer fab	AG8F-Agrate AG8 8
Product Description	DC-DC Converters		
P/N	L7987L	Assembly plant	SC-Tianshui Huatian-China (TSHT)
Product Group	AMS (Analog MEMS & Sensor Group)		
Product division	General Purpose Analog & RF Division POWER MANAGEMENT	Reliability Trials	PASS
Package	HTSSOP 16		
Silicon Process technology	BCD6S		

Version	Date	Pages	Created by	Approved by	Comment
1.0	June 2021	7	Antonio Russo	Giuseppe Lisi	Final Report

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1 APPLICABLE AND REFERENCE DOCUMENTS

Document reference	Short description
JESD47	Stress-Test-Driven Qualification of Integrated Circuits

2 RELIABILITY EVALUATION OVERVIEW

2.1 OBJECTIVES

This report contains the reliability evaluation of L7987L (UI76) HTSSOP 16 in the new assembly plant SC-Tianshui Huatian-China (TSHT). The reliability evaluation has been performed on three different assy lots as requested by JEDEC JESD47 for this type of change (new assembly plant).

2.1 CONCLUSION

Qualification Plan requirements have been defined accordingly to JESD47. We have completed the reliability trials on all 3 assy lots and have shown that the devices behave correctly against environmental tests (no failure). Moreover, the stability of electrical parameters during the accelerated tests demonstrates the ruggedness of the products and safe operation, which is consequently expected during their lifetime. More details are available below in test and results summary.

3 **CHANGE DESCRIPTION**

Qualification of new Assembly Plant SC-Tianshui Huatian-China (TSHT) for HTSSOP 16

4 **CONSTRUCTION NOTE**

	<i>UI76</i>
Wafer/Die fab. Information	
Wafer fab manufacturing location	AG8F-Agrate AG8 8
Technology	BCD6S
Die finishing back side	Cr/NiV/Au
Die size	2535 x 2259 um
Passivation type	TEOS/SiN/Polyimide
Assembly information	
Assembly site	SC-Tianshui Huatian-China (TSHT)
Package description	HTSSOP 16
Mold Compound	Epoxy
Frame	Pure Tin Plating Sn 100%
Bond Wire	1.2 mil Au

5 TESTS RESULTS SUMMARY

5.1 Test vehicle

Lot #	Commercial product	Rawline	Package	Product Line
1	L7987L	1RI0*UI76ADA	HTSSOP 16	UI7601
2				
3				

5.2 Test plan and results summary

Test	PC	Std ref.	Conditions	ss	Steps	SS			Note
						Lot 1	Lot 2	Lot 3	
Die Oriented Reliability trials									
HTSL	N	JESD22 A-103	Ta = 150°C	240	168 H	0/80	0/80	0/80	2
					500 H	0/80	0/80	0/80	
					1000 H	0/80	0/80	0/80	
Package Oriented Reliability trials									
PC	-	JESD22 A-113	Drying 24 H @ 125°C Store 192 H @ Ta=30°C Rh=60% Oven Reflow @ Tpeak=260°C 3 times	720	Final	Pass	Pass	Pass	
AC	Y	JESD22 A-102	Pa=2Atm / Ta=121°C	240	96 H	0/80	0/80	0/80	1
					168 H	0/80	0/80	0/80	
THB	Y	JESD22 A101	85 °C, 85 % RH, Vcc max	240	168 H	0/80	0/80	0/80	1
					500 H	0/80	0/80	0/80	
					1000 H	0/80	0/80	0/80	
TC	Y	JESD22 A-104	Ta = -65°C to 150°C	240	100cy	0/80	0/80	0/80	1
					500 cy	0/80	0/80	0/80	
					1000 cy	0/80	0/80	0/80	
Package Assembly Integrity trials									
WBP	-	M2011	30 wires, characterization	30	Final	Pass CPK>1.66	Pass CPK>1.66	Pass CPK>1.66	
WBS	-	JESD22-B116	30 balls, characterization	30	Final	Pass CPK>1.66	Pass CPK>1.66	Pass CPK>1.66	
Solderability	-	JESD22-B102	>95% lead coverage	15	Final	Pass	Pass	Pass	
Notes:									
1. Preconditioning with soak per J-STD-020 at rated moisture sensitivity level prior to acceleration stress testing									
2. Preconditioning without soak									

6 ANNEXES

6.1 Pin connections

Please refer to product datasheet

6.2 Package Mechanical data

Please refer to product datasheet

7 TEST DESCRIPTION

Test name	Description	Purpose
Die Oriented		
HTSL High Temperature Storage Life	The device is stored in unbiased condition at the max. temperature allowed by the package materials, sometimes higher than the max. operative temperature.	To investigate the failure mechanisms activated by high temperature, typically wire-bonds solder joint ageing, data retention faults, metal stress-voiding.
Package Oriented		
PC Preconditioning	The device is submitted to a typical temperature profile used for surface mounting devices, after a controlled moisture absorption.	As stand-alone test: to investigate the moisture sensitivity level. As preconditioning before other reliability tests: to verify that the surface mounting stress does not impact on the subsequent reliability performance. The typical failure modes are "pop corn" effect and delamination.
THB Temperature Humidity Bias	The device is biased in static configuration minimizing its internal power dissipation, and stored at controlled conditions of ambient temperature and relative humidity.	To evaluate the package moisture resistance with electrical field applied, both electrolytic and galvanic corrosion are put in evidence.
AC Auto Clave (Pressure Pot)	The device is stored in saturated steam, at fixed and controlled conditions of pressure and temperature.	To investigate corrosion phenomena affecting die or package materials, related to chemical contamination and package hermeticity.
TC Temperature Cycling	The device is submitted to cycled temperature excursions, between a hot and a cold chamber in air atmosphere.	To investigate failure modes related to the thermo-mechanical stress induced by the different thermal expansion of the materials interacting in the die-package system. Typical failure modes are linked to metal displacement, dielectric cracking, molding compound delamination, wire-bonds failure, die-attach layer degradation.

Test name	Description	Purpose
WBS Wire Bond Shear	A process in which an instrument uses a chisel shaped tool to shear or push a ball or wedge/stitch bond off the bonding surface. The force required to cause this separation is recorded and is referred to as the bond shear strength. The bond shear strength of a ball bond, when correlated to the diameter of the ball bond, is an indicator of the quality of the metallurgical bond between the ball bond and the die bonding surface metallization.	This test establishes a procedure for determining the strength of the interface between a ball bond and a package bonding surface. This strength measurement is extremely important in determining the integrity of the metallurgical bond which has been formed.
WBP Wire Bond Pull	The apparatus for this test shall consist of suitable equipment for applying the specified stress to lead wire or terminal as required in the specified test condition. A calibrated measurement and indication of the applied stress in grams force (gf) shall be provided by equipment capable of measuring stresses.	The purpose of this test is to measure bond strengths, evaluate bond strength distributions, or determine compliance with specified bond strength requirements of the applicable acquisition document.